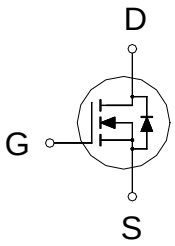
杰力科技股份有限公司
Excelliance MOS Corporation

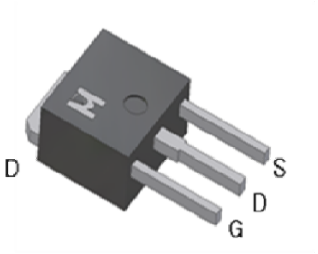
EMBJ0N25CS

N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV_{DSS}	250V
$R_{DSON\ (MAX.)}$	1Ω
I_D	4.4A





UIS, Rg 100% Tested

Pb-Free Lead Plating & Halogen Free

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_C = 25 °C	I_D	4.4	A
	T_C = 100 °C		2.6	
Pulsed Drain Current[1]		I_{DM}	17.6	
Avalanche Current		I_{AS}	1	
Avalanche Energy	L = 3mH, ID=1A, RG=25Ω	E_{AS}	1.5	mJ
Repetitive Avalanche Energy[2]	L = 1mH	E_{AR}	0.5	
Power Dissipation	T_C = 25 °C	P_D	29	W
	T_C = 100 °C		11	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		4.2	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

[1]Pulse width limited by maximum junction temperature.

[2]Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS (T_C = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 10mA	250			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	1	2	3	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 200V, V_{GS} = 0V			1	μA
		V_{DS} = 200V, V_{GS} = 0V, T_J = 125 °C			25	
On-State Drain Current[1]	$I_{D(ON)}$	V_{DS} = 10V, V_{GS} = 10V	4.4			A
Drain-Source On-State Resistance[1]	$R_{DS(ON)}$	V_{GS} = 10V, I_D = 2.2A		0.82	1.0	Ω
		V_{GS} = 5V, I_D = 1.1A		0.90	1.1	
Forward Transconductance[1]	g_{fs}	V_{DS} = 50V, I_D = 2.2A		2.3		S
DYNAMIC						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		1224		pF
Output Capacitance	C_{oss}			27		
Reverse Transfer Capacitance	C_{rss}			23		
Gate Resistance	R_g	V_{GS} = 15mV, V_{DS} = 0V, f = 1MHz		2.0		Ω
Total Gate Charge[1,2]	Q_g	V_{DS} = 200V, V_{GS} = 10V, I_D = 2.2A		32		nC
Gate-Source Charge[1,2]	Q_{gs}			4		
Gate-Drain Charge[1,2]	Q_{gd}			8.1		
Turn-On Delay Time[1,2]	$t_{d(on)}$	V_{DS} = 125V, I_D = 1A, V_{GS} = 10V, R_G = 6Ω		10		nS
Rise Time[1,2]	t_r			65		
Turn-Off Delay Time[1,2]	$t_{d(off)}$			20		
Fall Time[1,2]	t_f			35		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_C = 25 °C)						
Continuous Current	I_S				4.4	A
Pulsed Current[3]	I_{SM}				17.6	
Forward Voltage[1]	V_{SD}	I_F = I_S, V_{GS} = 0V			1.3	V
Reverse Recovery Time	t_{rr}	I_F = 4.4A, dI_F/dt = 100A / μS		125		nS
Reverse Recovery Charge	Q_{rr}			500		nC

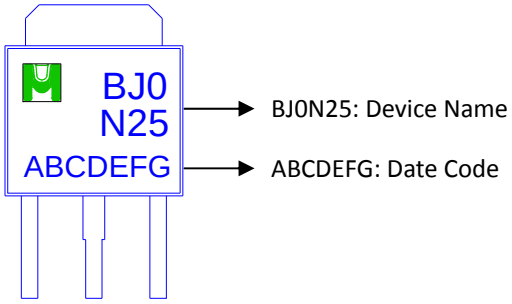
[1]Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

[2]Independent of operating temperature.

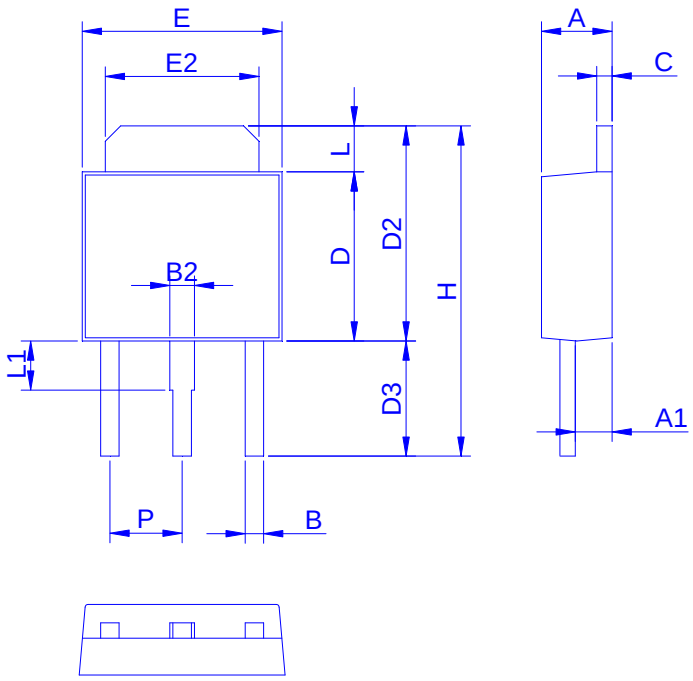
[3]Pulse width limited by maximum junction temperature.

Ordering & Marking Information:

Device Name: EMBJ0N25CS for IPAK (TO-251)



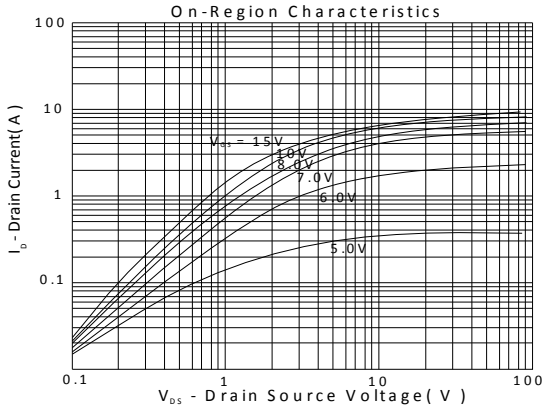
Outline Drawing

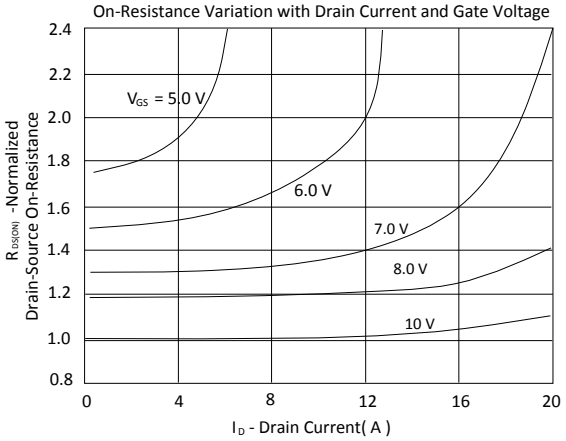


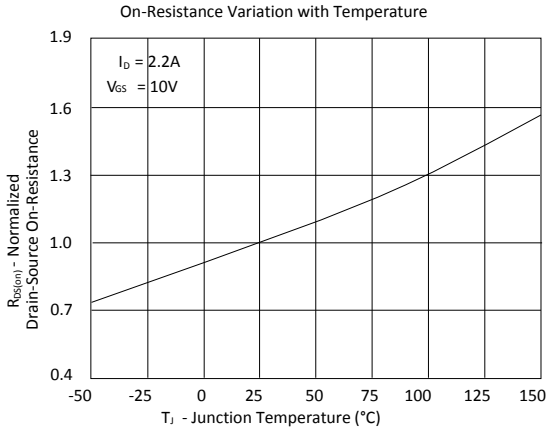
Dimension in mm

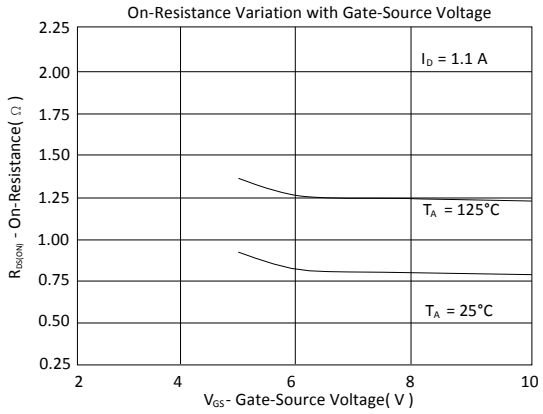
Dimension	A	A1	B	B2	C	D	D2	D3	E	E2	H	L	L1	P
Min.	2.10	0.90	0.40	0.60	0.40	5.30	6.70	3.40	6.30	4.80	10.2	0.89	0.90	2.10
Max.	2.50	1.50	0.90	1.15	0.60	6.25	7.30	4.30	6.80	5.50	11.5	1.40	1.80	2.50

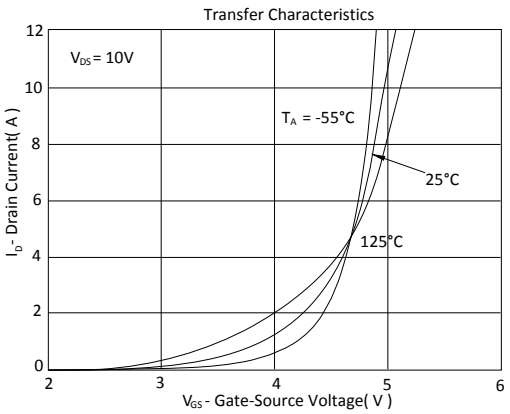
TYPICAL CHARACTERISTICS

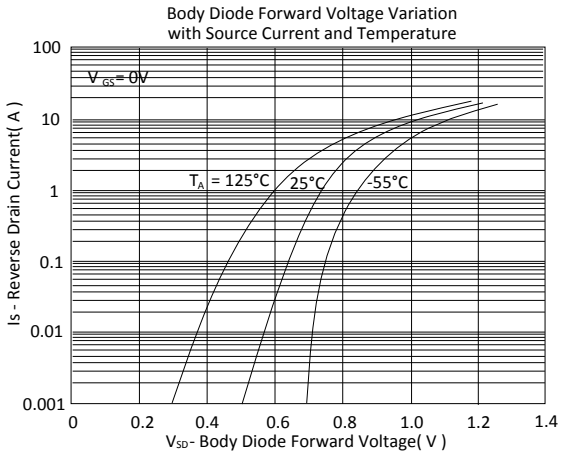




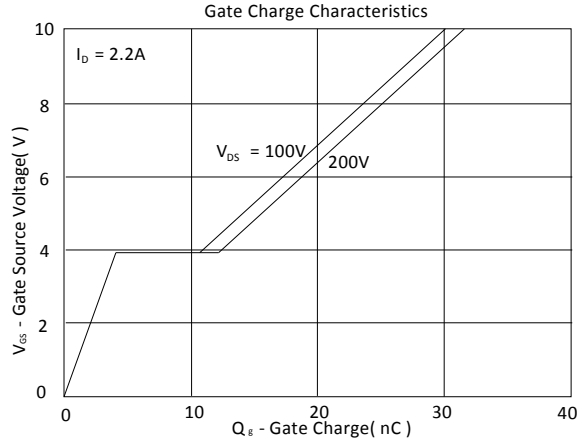




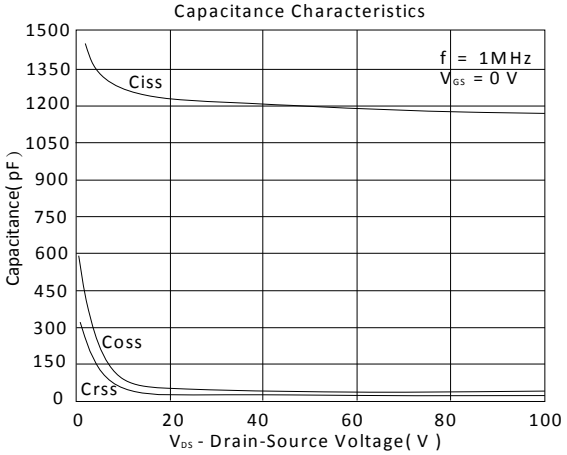




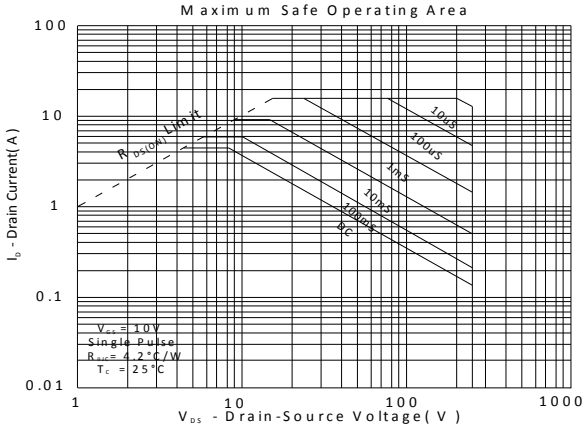
Gate Charge Characteristics



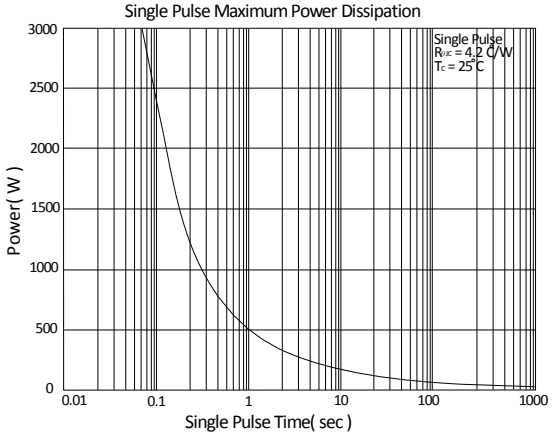
Capacitance Characteristics



Maximum Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve